

IN THE CLAIMS

Please amend the claims as follows.

1. (Previously Presented) For use in a transfer molding process of the type that uses a transfer mold to encapsulate portions of an integrated circuit within a molding compound, a method for using a pre-formed film in said transfer molding process, said method comprising the steps of:

providing a film of compliant material;

pre-forming said film of compliant material to approximately conform a shape of said film to a mold cavity surface of said transfer mold; and

placing said pre-formed film of compliant material within said transfer mold adjacent to said mold cavity surface of said transfer mold.

2. (Previously Presented) The method as set forth in Claim 1 wherein said step of pre-forming said film of compliant material is carried out immediately before said film is placed within said transfer mold.

3. (Cancelled).

4. (Original) The method as set forth in Claim 1 wherein said step of pre-forming said film of compliant material to conform a shape of said film to a mold cavity surface of said transfer mold comprises one of: embossing said film and stamping said film.

5. (Original) The method as set forth in Claim 1 further comprising the steps of:
placing said transfer mold over an integrated circuit die on an integrated circuit substrate;
filling said mold cavity of said transfer mold with liquefied molding compound;
allowing said molding compound to solidify; and
removing said transfer mold from said integrated circuit die and said integrated circuit substrate after said molding compound has solidified.

6. (Cancelled).

7. (Currently Amended) For use in a transfer molding process of the type that uses a transfer mold to encapsulate portions of an integrated circuit within a molding compound, a method for using a pre-formed film in said transfer molding process, said method comprising the steps of:

providing a tape made of a film of compliant material;

pre-forming a plurality of portions of said tape to ~~at least approximately~~ conform a shape of each of said plurality of portions of said tape to a mold cavity surface of said transfer mold; and

placing one of said plurality of portions of said tape within said transfer mold adjacent to said mold cavity surface of said transfer mold during the transfer molding process.

8. (Previously Presented) The method as set forth in Claim 7 wherein said step of pre-forming said portion of said tape is carried out immediately before said portion of said tape is placed within said transfer mold.

9. (Previously Presented) The method as set forth in Claim 7 wherein said portion of said tape is pre-formed to a shape that approximately conforms to a shape of said mold cavity surface of said transfer mold.

10. (Previously Presented) The method as set forth in Claim 7 wherein said step of pre-forming said portion of said tape to conform a shape of said portion of said tape to a mold cavity surface of said transfer mold comprises one of: embossing said portion of said tape and stamping said portion of said tape.

11. (Previously Presented) The method as set forth in Claim 7 further comprising the steps of:

placing said transfer mold over an integrated circuit die on an integrated circuit substrate;

filling said mold cavity of said transfer mold with liquefied molding compound;

allowing said molding compound to solidify; and

removing said transfer mold from said integrated circuit die and said integrated circuit substrate after said molding compound has solidified.

12. (Previously Presented) For use in a transfer molding process of the type that uses a top half of a transfer mold and a bottom half of a transfer mold to encapsulate portions of an integrated circuit within a molding compound, a method for using a pre-formed film in said transfer molding process, said method comprising the steps of:

providing a first film of compliant material;

pre-forming said first film of compliant material to approximately conform a shape of said first film to a mold cavity surface of said top half of said transfer mold;

placing said pre-formed first film of compliant material within said top half of said transfer mold adjacent to said mold cavity surface of said top half of said transfer mold;

providing a second film of compliant material;

pre-forming said second film of compliant material to approximately conform a shape of said second film to a mold cavity surface of said bottom half of said transfer mold; and

placing said pre-formed second film of compliant material within said bottom half of said transfer mold adjacent to said mold cavity surface of said bottom half of said transfer mold.

13. (Previously Presented) The method as set forth in Claim 12 wherein said step of pre-forming said first film of compliant material is carried out immediately before said first film is placed within said top half of said transfer mold; and

wherein said step of pre-forming said second film of compliant material is carried out before said second film is placed within said bottom half of said transfer mold.

14. (Cancelled).

15. (Original) The method as set forth in Claim 12 wherein said step of pre-forming said first film of compliant material to conform a shape of said first film to a mold cavity surface of said top half of said transfer mold comprises one of: embossing said first film and stamping said first film; and

wherein said step of pre-forming said second film of compliant material to conform a shape of said second film to a mold cavity surface of said bottom half of said transfer mold comprises one of: embossing said second film and stamping said second film.

16. (Original) The method as set forth in Claim 12 further comprising the steps of:

placing said top half of said transfer mold and said bottom half of said transfer mold around an integrated circuit die on an integrated circuit substrate to form a mold cavity around said integrated circuit die on said integrated circuit substrate;

filling said mold cavity of said transfer mold with liquefied molding compound;

allowing said molding compound to solidify; and

removing said transfer mold from said integrated circuit die and said integrated circuit substrate after said molding compound has solidified.

Claims 17-29 (Cancelled).

30. (Previously Presented) The method of Claim 1, wherein:

pre-forming the film comprises pre-forming a plurality of portions of the film to approximately conform a shape of each of the plurality of portions of the film to the mold cavity surface of the transfer mold; and

placing the pre-formed film within the transfer mold comprises placing one of the plurality of portions of the film within the transfer mold.

31. (Previously Presented) The method of Claim 30, further comprising cutting the pre-formed film to separate at least some of the plurality of portions of the film.

32. (Previously Presented) The method of Claim 7, further comprising cutting the pre-formed tape to separate at least some of the plurality of portions of the tape.

33. (Previously Presented) The method of Claim 7, wherein the film comprises a silicone coated latex saturated paper liner.

34. (Previously Presented) The method of Claim 12, wherein:
pre-forming the first film comprises pre-forming a plurality of portions of the first film to approximately conform a shape of each of the plurality of portions of the first film to the mold cavity surface of the top half of the transfer mold;

placing the pre-formed first film within the top half of the transfer mold comprises placing one of the plurality of portions of the first film within the top half of the transfer mold;

pre-forming the second film comprises pre-forming a plurality of portions of the second film to approximately conform a shape of each of the plurality of portions of the second film to the mold cavity surface of the bottom half of the transfer mold; and

placing the pre-formed second film within the bottom half of the transfer mold comprises placing one of the plurality of portions of the second film within the bottom half of the transfer mold.

35. (Previously Presented) The method of Claim 34, further comprising:
cutting the pre-formed first film to separate at least some of the plurality of portions of
the first film; and
cutting the pre-formed second film to separate at least some of the plurality of portions of
the second film.

36. (Previously Presented) The method of Claim 12, wherein:
each of the first and second films comprises a silicone coated latex saturated paper liner;
and
pre-forming the first and second films comprises pre-forming the silicone coated latex
saturated paper liners while edges of the films are unconstrained.